

English [PRODUCTS](#) [APPLICATIONS](#) [DESIGN SUPPORT](#) [TRAINING](#) [SAMPLE & BUY](#) [ABOUT US](#) [Contact Us](#) [myMicrochip Login](#)Product Change Notification - JAON-13KCMB362 [\(Printer Friendly\)](#)**Date:** 24 Apr 2015**Notification subject:** CCB 1581 Initial Notice:Qualification of NSEB assembly site as an additional site for USB3750 and USB3751 device families in 16L QFN package using palladium coated copper with gold flash (CuPdAu) wire**Notification text:** **PCN Status:**
Initial notification**Microchip Parts Affected:**

See attachments of affected catalog part numbers (CPN) labeled as...

[PCN_JAON-13KCMB362_Affected_CPN.xls](#)[PCN_JAON-13KCMB362_Affected_CPN.pdf](#)**Description of Change:**

Qualification of NSEB assembly site as an additional site for USB3750 and USB3751 device families in 16L QFN package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at SCC site using 8290 die attach epoxy, G770 molding compound and matte tin plating.

Post Change:

Assembled at SCC site using 8290 die attach epoxy, G770 molding compound and matte tin plating and assembled at NSEB using 8600 die attach epoxy, G700LTD molding compound and NiPdAu (PPF) plating.

Impacts to Data Sheet:

None

Reason for Change:

To improve productivity by qualifying NSEB as an additional assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

October 1, 2015 (date code: 1540)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:**April 24, 2015:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_JAON-13KCMB362_Qual_Plan.pdf](#)
[PCN_JAON-13KCMB362_Affected_CPN.pdf](#)
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